

表面活性化活性化接合

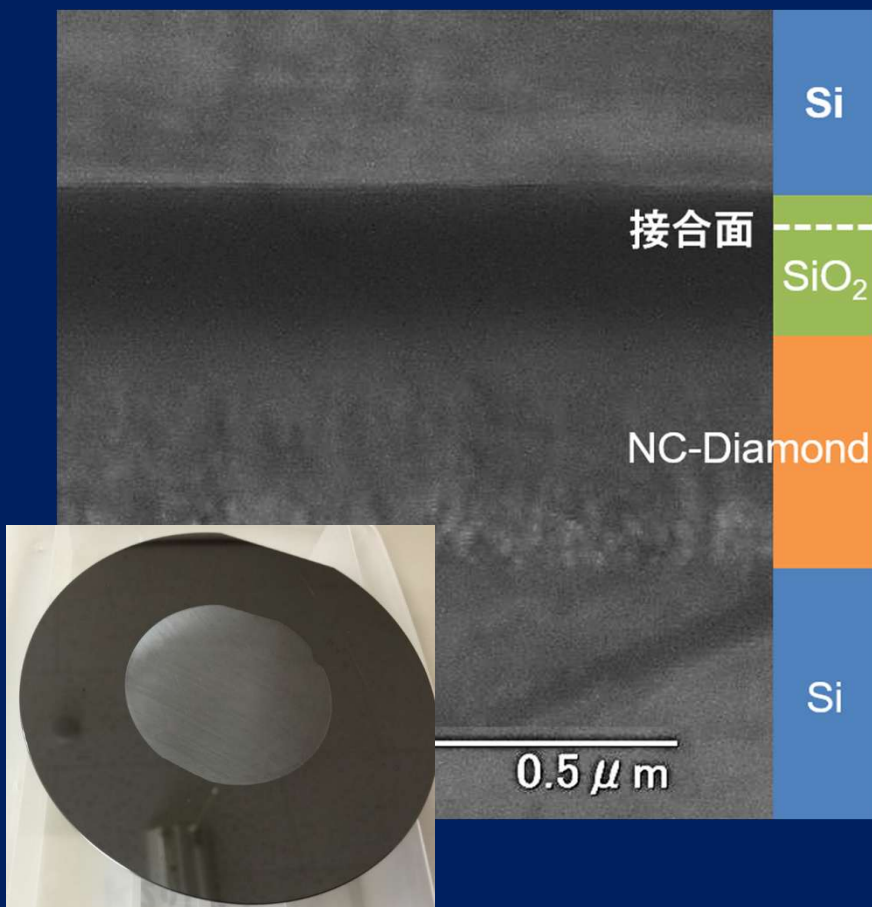


図1: Silicon on Diamond基板

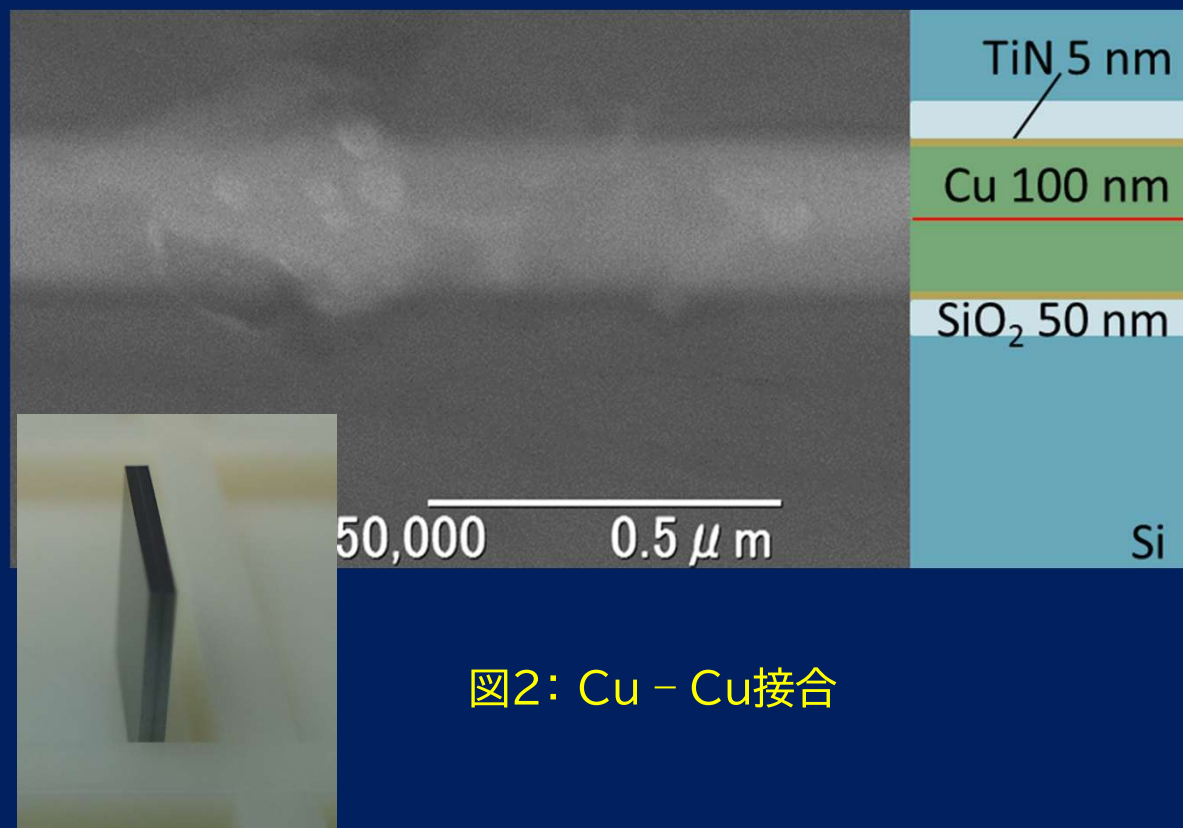


図2: Cu - Cu接合

- 1) The silicon on diamond structure by low-temperature bonding technique:
The 65th Electronic Components and Technology Conference (ECTC 2015) pp. 187-192.
- 2) Reduced Operating Temperature of Active Layer Si Covered by Nanocrystalline Diamond Film
Journal of Materials Science: Materials in Electronics, Vol.28, Issue.1, January 2017, pp.617-624.
- 3) Fabrication of Silicon on Diamond Structure with an Ultra-Thin SiO₂ Bonding Layer by Sputter Etching Method: Jpn. J. Appl. Phys. Vol 57, 06HJ08 (2018).